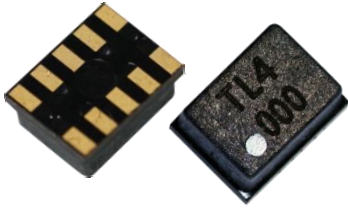


Applications

- DMI Gen2 & DMI Gen3 in ATE

Features

- Small footprint and integrated loopback circuit with 4 inductors
 - > Inductor is manufactured by MEMS (Micro Electro Mechanical Systems)
 - > Inductor is designed specifically for broadband applications : up to 6.5GHz
- Surface mounted component with high reliability
- Package size : 3.45 x 4.55 x 2.30mm (W x L x H mm)
- Package cap is hermetically sealed and protects MEMS inductors



Electrical Specification		Environmental Specification	
Inductance*1 (Tolerance : ±5%)	59.9nH @ 5MHz 58.1nH @ 100MHz	Thermal Shock	200 cycles, -65°C ~ +150°C
SRF*2 (Typ.)	6.69GHz	Pressure Cooker Test	+130°C, 85% RH, 96Hrs
Idc*3 (Max)	300mA	Operating Temperature Range	-55°C ~ +85°C
DCR*4	1.97±0.1Ω		

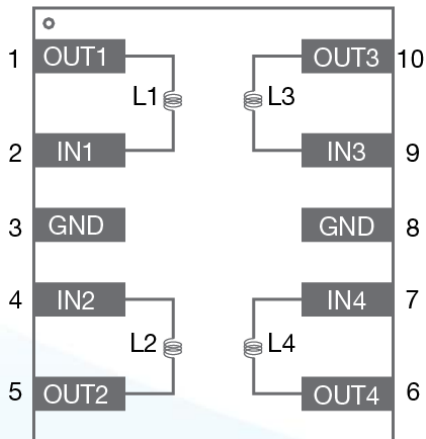
*1. Measurement Instrument : Impedance Analyzer Agilent 4294 & 42941A(Probe Kit)

*2. Measurement Instrument : VNA Agilent 8720ES

*3. Idc Measurement Condition : The DC resistance changes were observed by supplying 5V and maintaining 300mA current for 30 minutes at room temperature

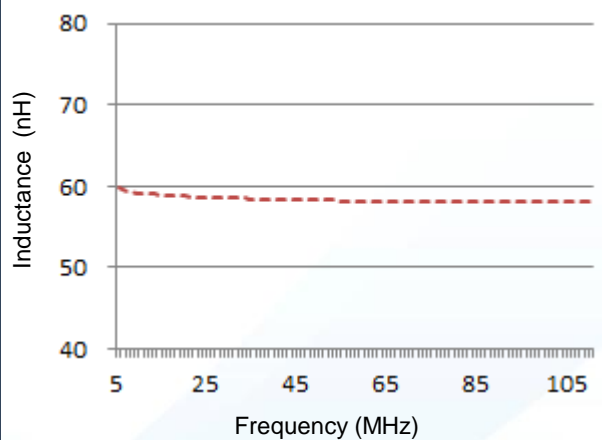
*4. Measurement Instrument : Keithley 2000

Pin Assignment

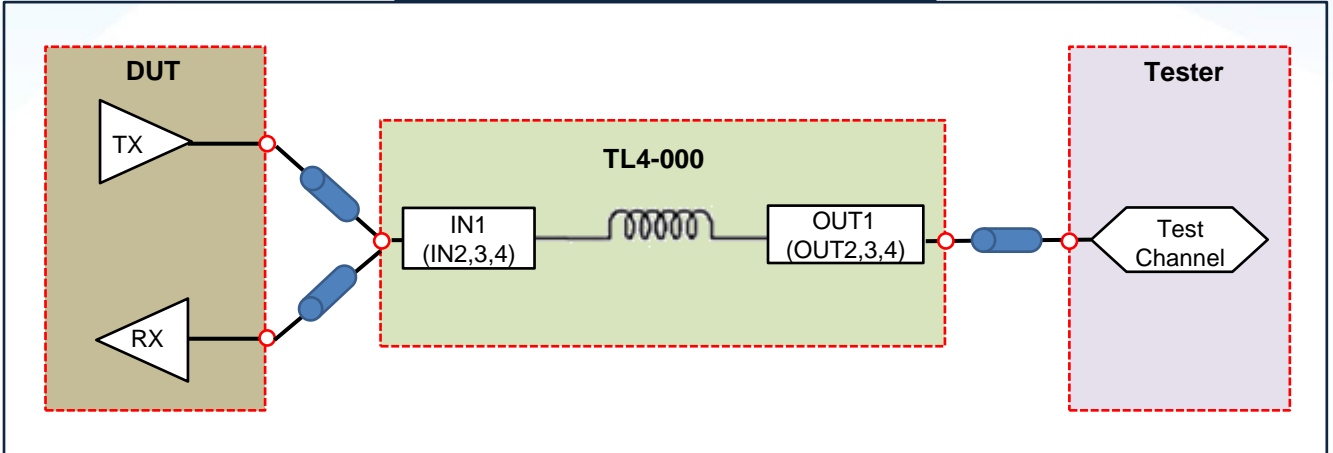


- L1~L4 : MEMS Inductor

Inductance vs Frequency

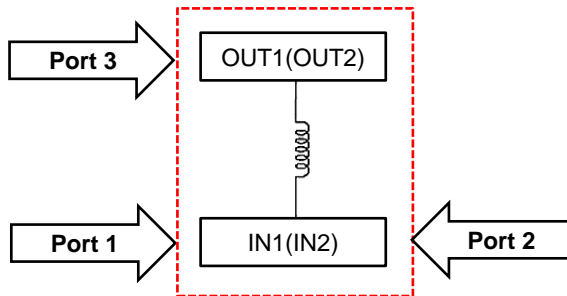


Typical Application

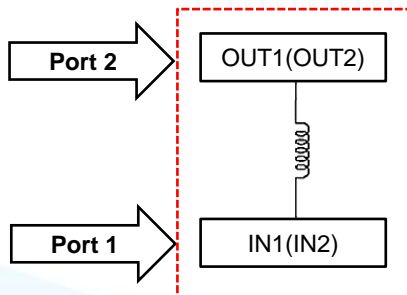


S-Parameter Measurement Set up

- Loopback Path

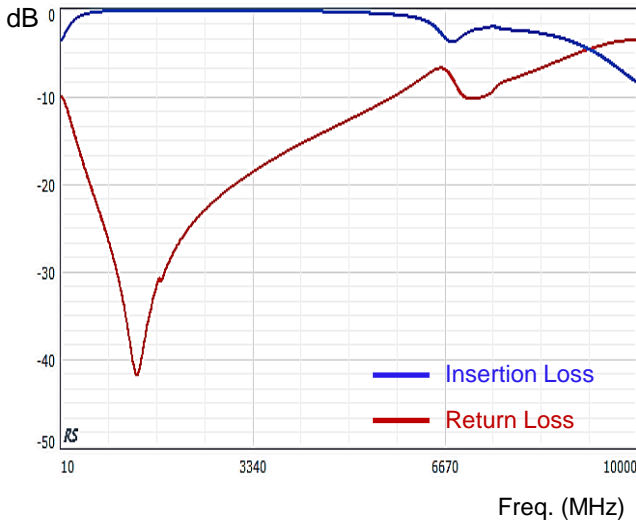


- Inductor Path (Test Channel Connection)

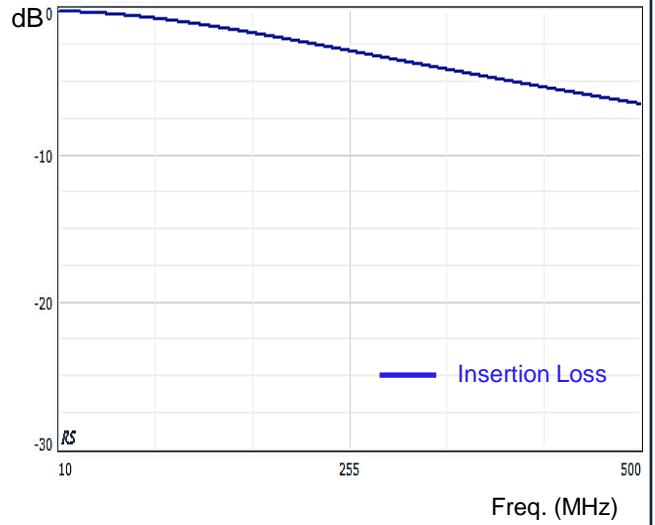


S-Parameter

- Loopback Path S-Parameter



- Inductor Path S-Parameter (Test Channel Connection)



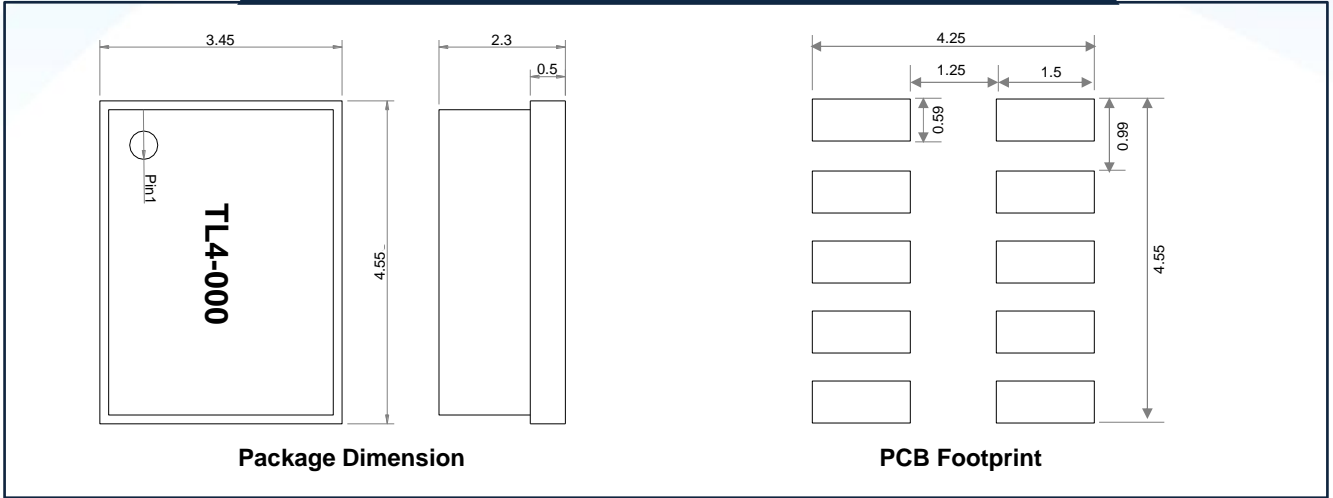
- Loopback Path S-Parameter

Frequency	Insertion Loss(dB)	Return Loss(dB)
0.5 GHz	-0.354	-19.40
1.0 GHz	-0.083	-30.20
2.0 GHz	-0.001	-27.20
3.0 GHz	-0.038	-20.00
4.0 GHz	-0.115	-15.90
5.0 GHz	-0.255	-12.50
6.0 GHz	-0.674	-8.97
7.0 GHz	-2.800	-9.85

- Inductor Path (Test Channel Connection) S-Parameter

Frequency	Insertion Loss(dB)
100 MHz	-0.725
200 MHz	-2.020
300 MHz	-3.550
400 MHz	-5.060

PKG Dimension & PCB Footprint (Unit : mm)



SMT Reflow Profile (for Lead Free)

Parameter	Specification
Preheat and Soak [Temperature min (T _{smin}) Temperature max (T _{smax}) Time (T _{smin} to T _{smax})	150 °C 200 °C 60~120 seconds
Average ramp-up rate (T _{smax} to T _p)	3 °C/second maximum
Liquidous temperature (T _L) Time at liquidous (t _L)	217 °C 60~150 seconds
Peak temperature in reflow (T _p)	260 °C (+0/-5 °C)
Time(t _p) within 5 °C of the specified classification temperature (T _c)	20 seconds
Average ramp-down rate (T _p to T _{smax})	6 °C/second max
Time 25 °C to peak temperature	8 minutes max

[Note] Prior to SMT, bake TL4-000 for 1.5hour at 120 °C if it was stored over 3days at room temperature after unpacking

